

2mm FLAT TOP LED LAMP

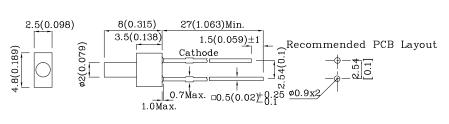
Features

- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS Compliant









Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Green (GaP)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P_{D}	62.5	mW	
Operating Temperature	T_A -40 ~ +85		°C	
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

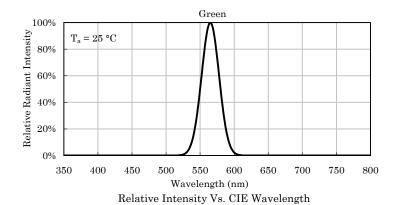
Operating Characteristics (T _A =25°C)		Green (GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.4	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =10mA)	λP	565*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =10mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

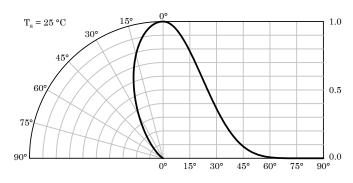
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous\ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}10\text{mA}) \\ mcd \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XLUG13D	Green	GaP	Green Diffused	6*	11*	565*	50°

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



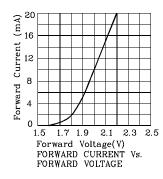


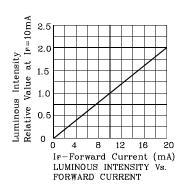


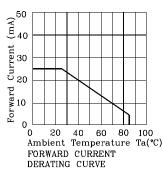


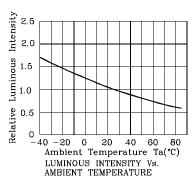
Spatial Distribution

Green

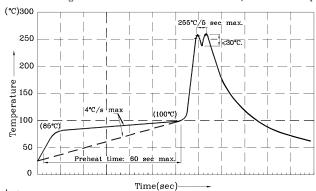








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes: Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C$ \sim $255^{\circ}C$ for 3 sec

(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above $85\,^\circ\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous Intensity / Luminous Flux: +/-15%

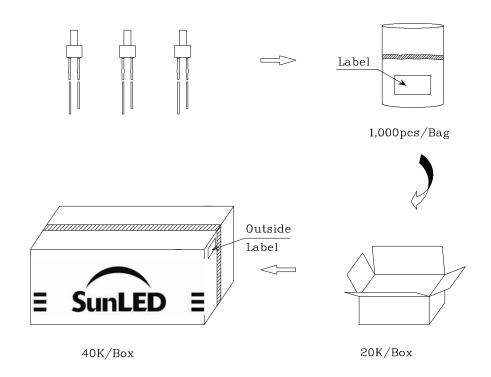
3. Forward Voltage: +/-0.1V

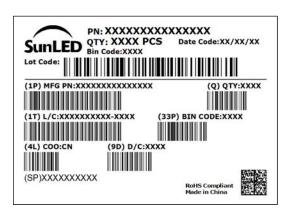
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





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